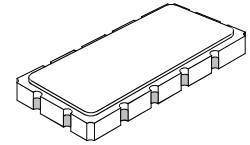


- **Low Insertion Loss**
- **Excellent Selectivity**
- **Hermetic 13.3 X 6.5 mm Surface-mount Case**
- **Single-ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**



**PX1004-1**

**82.2 MHz  
SAW Filter**



**SM13365-12**

**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any 2 Terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

**Electrical Characteristics**

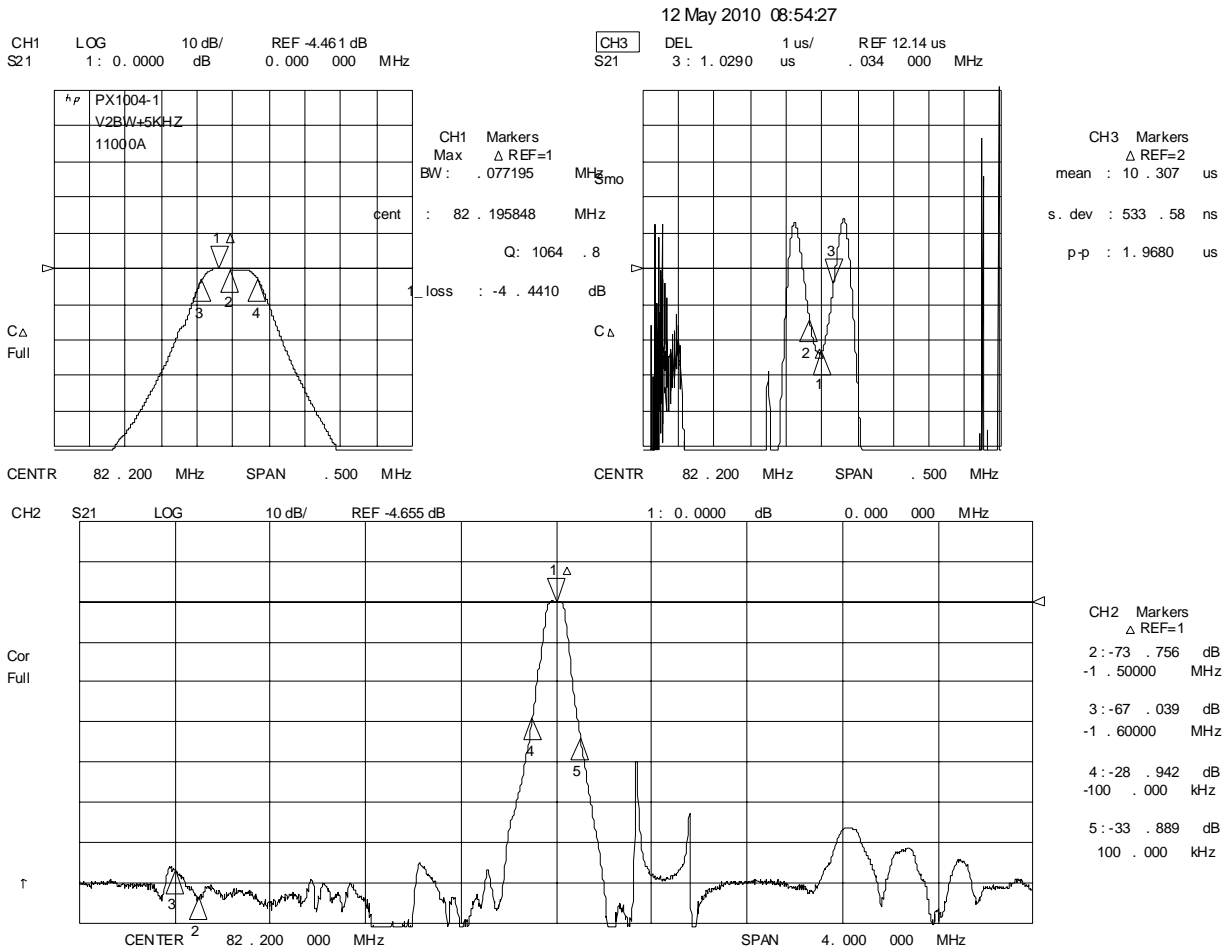
Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	$f_c$		82.20			MHz
Passband Insertion Loss at $f_c$ 3 dB Passband Amplitude Ripple over $f_c \pm 15$ kHz Group Delay Variation over $f_c \pm 17$ kHz	IL			3.0	5.5	dB
	$BW_3$		$\pm 25$	$\pm 42$		kHz
					1.0	dB <sub>P-P</sub>
		GDV			6.0	$\mu$ s <sub>P-P</sub>
Third-Order Intermod. for -20 dBm tones at $f_c \pm 100$ & 200 kHz					-95	dBm
Rejection $f_c \pm 100$ kHz $f_c - 1500$ kHz to $f_c - 1600$ kHz Ultimate			11	16		dB
			65			
				65		
Operating Temperature Range	$T_A$		-20		+70	°C

Impedance Matching to 50 $\Omega$ unbalanced	External L-C
Case Style	SM13365-12 13.3 X 6.5 mm Nominal Footprint

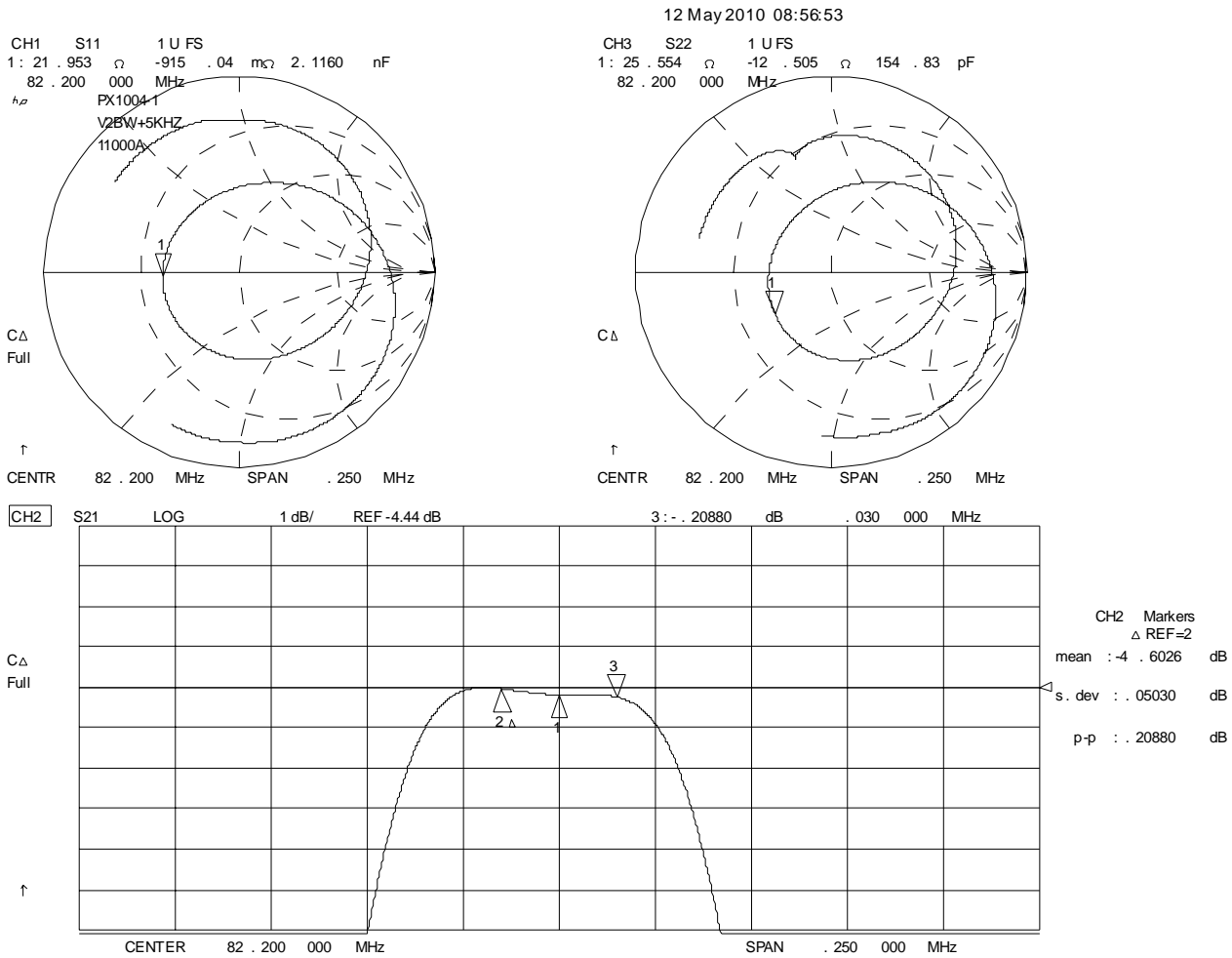
 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**  
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

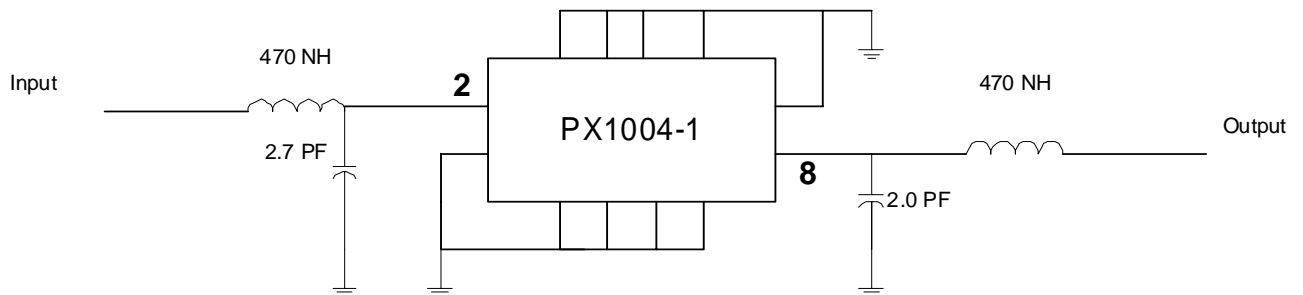
## Amplitude and Group Delay Plots



## Input/Output Impedance and Passband Amplitude Plots

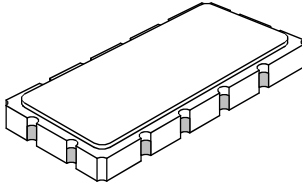


## Filter Test Circuit



SM13365-12 Case

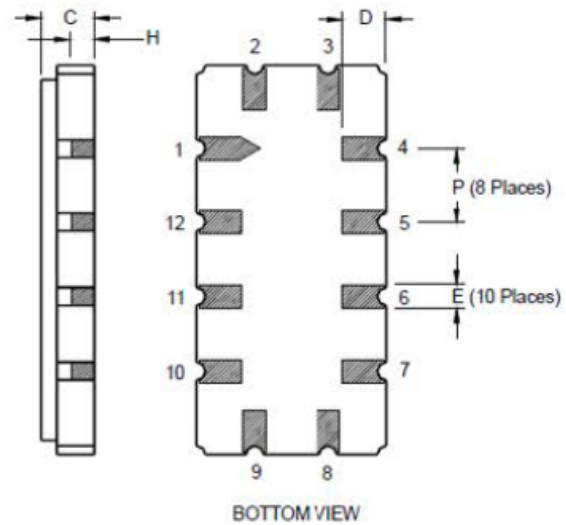
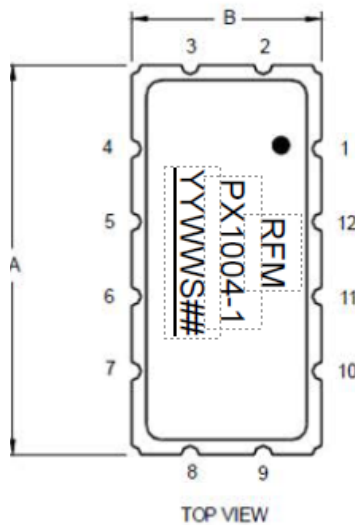
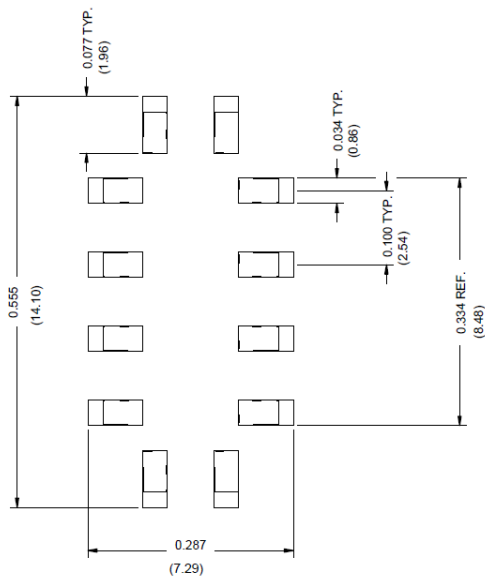
12-Terminal Ceramic Surface-Mount Case  
13.3 x 6.5 mm Nominal Footprint



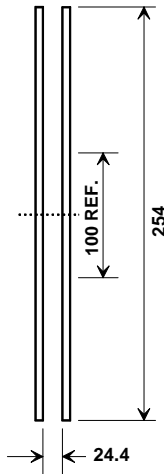
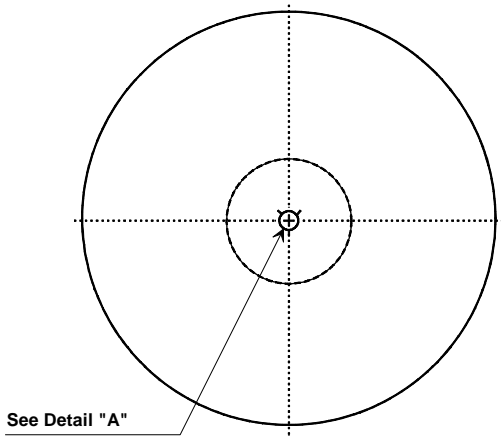
Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	13.08	13.31	13.60	0.515	0.524	0.535
B	6.27	6.50	6.80	0.247	0.256	0.268
C		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic

Symbolization:  
 YY = Year  
 WW = Week  
 S = Shift  
 ## = Sequence Code

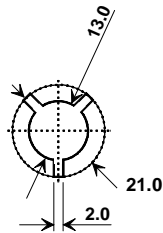


Tape and Reel Specifications



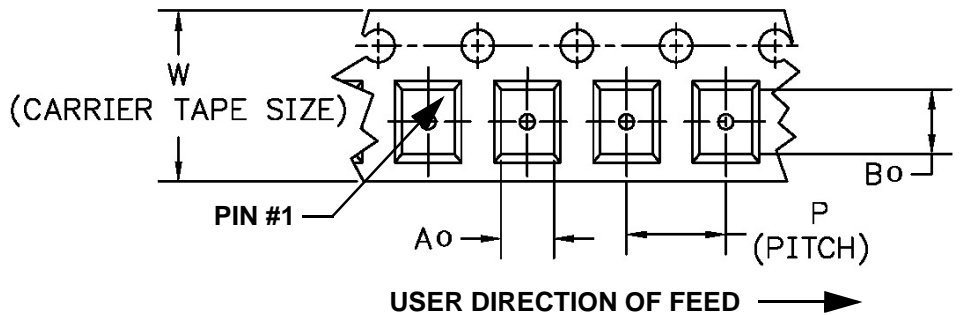
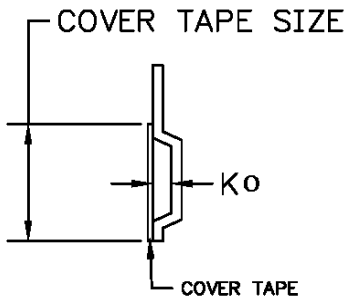
Tape and Reel Standard per ANSI/EIA-481

Quantity Per Reel
1000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	7.0 mm
Bo	13.8 mm
Ko	2.0 mm
Pitch	12.0 mm
W	24.0 mm



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

